

APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾	STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾	
	VOLTAGE	50 V AC	STORAGE HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)	
	CURRENT	0.5 A	OPERATING HUMIDITY RANGE		
SPECIFICATIONS					
ITEM	TEST METHOD		REQUIREMENTS	QT	AT
CONSTRUCTION					
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x	x
MARKING	CONFIRMED VISUALLY.			x	x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE	100 mA(DC OR 1000Hz)		70 mΩ MAX .	x	—
INSULATION RESISTANCE	100 V DC.		100 MΩ MIN.	x	—
VOLTAGE PROOF	150 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x	x
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES	MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 42 N MAX. WITHDRAWAL FORCE: 5.2 N MIN.	x	—
MECHANICAL OPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
VIBRATION	FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 AXIAL DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
SHOCK	490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 BOTH AXIAL DIRECTIONS.			x	—
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. ② INSULATION RESISTANCE :100 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER:WITHIN 2~3 MIN)			x	—
COLD	EXPOSED AT -55°C, 96 h		① CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
DRY HEAT	EXPOSED AT 85°C, 96 h			x	—
SULFUR DIOXIDE	EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		① NO DEFECT SUCH AS CORROSION WHICH IMPAIRS THE FUNCTION OF CONNECTOR. ② CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.	x	—
RESISTANCE TO SOLDERING HEAT	1)REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.			NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	x	—
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB.	△				
			APPROVED	HS. OKAWA	12. 03. 06
			CHECKED	KI. HIROKAWA	12. 03. 06
			DESIGNED	KT. DOI	12. 03. 02
Unless otherwise specified, refer to JIS-C-5402.			DRAWN	KT. DOI	12. 03. 02
Note	QT:Qualification Test AT:Assurance Test X:Applicable Test		DRAWING NO.	ELC4-336339-00	
HRS	SPECIFICATION SHEET		PART NO.	FX20-60S-0. 5SV	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL570-1102-8-00	△ 1/1